

IN THE CLAIMS:

Claims 1-16 (cancelled)

17. (New) A method for fabricating a semiconductor package, comprising the steps of:

a) placing a leadframe which defines a space for accommodating a semiconductor chip and includes a plurality of leads which each have a bottom surface onto an adhesive tape;

b) placing a semiconductor chip having a bottom surface and a plurality of bond pads onto the adhesive tape within the space defined by the leadframe;

c) electrically connecting at least one of the bond pads of the semiconductor chip to one of the leads;

d) at least partially encapsulating the semiconductor chip and the leads with an encapsulant material to form a package body; and

e) removing the adhesive tape from the package body such that the bottom surface of each of the leads and the bottom surface of the semiconductor chip are exposed in the package body.

18. (New) The method of Claim 17 further comprising the step of:

f) removing portions of the leadframe which protrude from the package body from the semiconductor package.

19. (New) The method of Claim 17 wherein steps (a) and (b) each comprise applying pressure to the leadframe and to the semiconductor chip to firmly affix the leadframe and the semiconductor chip to the adhesive tape.

20. (New) The method of Claim 17 wherein:

step (c) comprises electrically connecting the bond pads of the semiconductor chip to respective ones of the leads via conductive wires; and

step (e) comprises encapsulating the wires with the encapsulant material.

21. (New) The method of Claim 17 wherein steps (d) comprises partially encapsulating the leads such that an outer end of each of the leads is exposed in the package body.

22. (New) A method of fabricating a semiconductor package, comprising the steps of:

a) placing a leadframe defining a space for accommodating a semiconductor chip and including a ground ring which has a bottom surface and a plurality of leads which each have a bottom surface onto an adhesive tape;

b) placing a semiconductor chip having a bottom surface and a plurality of bond pads onto the adhesive tape within the space defined by the leadframe;

c) electrically connecting at least one of the bond pads of the semiconductor chip to one of the leads and at least one of the bond pads to the ground ring;

d) at least partially encapsulating the semiconductor chip, the ground ring, and the leads with an encapsulant material to form a package body; and

e) removing the adhesive tape from the package body such that the bottom surface of each of the leads, the bottom surface of the ground ring, and the bottom surface of the semiconductor chip are exposed in the package body.

23. (New) The method of Claim 22 further comprising the step of:

f) removing portions of the leadframe which protrude from the package body from the semiconductor package.

24. (New) The method of Claim 22 wherein steps (a) and (b) each comprise applying pressure to the leadframe and to the semiconductor chip to firmly affix the leadframe and the semiconductor chip to the adhesive tape.

25. (New) The method of Claim 22 wherein:

step (c) comprises electrically connecting the bond pads of the semiconductor chip to respective ones of the leads via conductive wires; and

step (e) comprises encapsulating the wires with the encapsulant material.

26. (New) The method of Claim 22 wherein steps (d) comprises partially encapsulating the leads such that an outer end of each of the leads is exposed in the package body.

27. (New) A method for fabricating a semiconductor package, comprising the steps of:

a) placing a leadframe including a chip paddle having a bottom surface and a plurality of leads which each have a bottom surface onto an adhesive tape;

b) attaching a semiconductor chip having a plurality of bond pads to the chip paddle;

c) electrically connecting at least one of the bond pads of the semiconductor chip to one of the leads;

d) at least partially encapsulating the semiconductor chip, the leads and the chip paddle with an encapsulant material to form a package body;

e) removing the adhesive tape from the package body such that the bottom surface of each of the leads and the bottom surface of the chip paddle are exposed in the package body.

28. (New) The method of Claim 27 further comprising the step of:

f) removing portions of the leadframe which protrude from the package body from the semiconductor package.

29. (New) The method of Claim 27 wherein step (a) comprises applying pressure to the leadframe to firmly affix the leadframe to the adhesive tape.

30. (New) The method of Claim 27 wherein:

step (c) comprises electrically connecting the bond pads of the semiconductor chip to respective ones of the leads via conductive wires; and

step (e) comprises encapsulating the wires with the encapsulant material.

31. (New) The method of Claim 27 wherein steps (d) comprises partially encapsulating the leads such that an outer end of each of the leads is exposed in the package body.

32. (New) The method of Claim 27 wherein step (b) comprises attaching the semiconductor chip to the chip paddle via an adhesive.